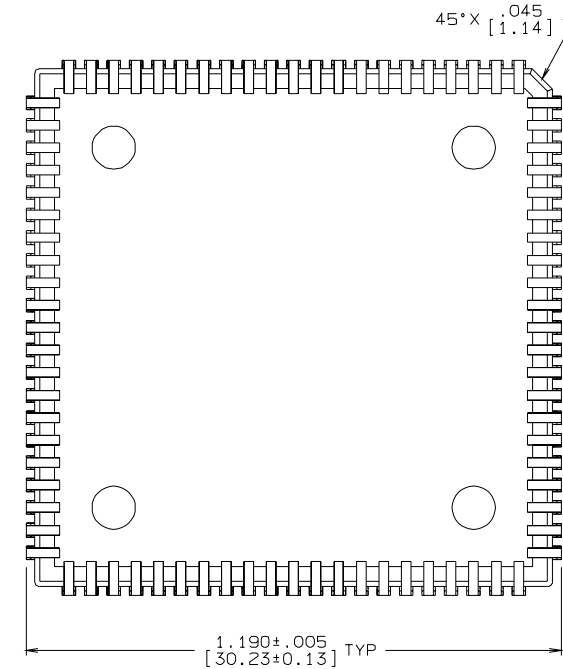
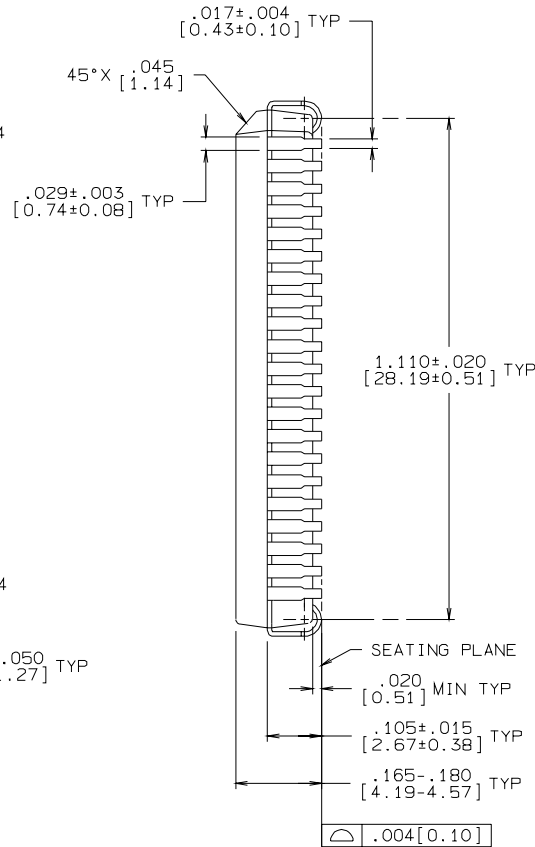
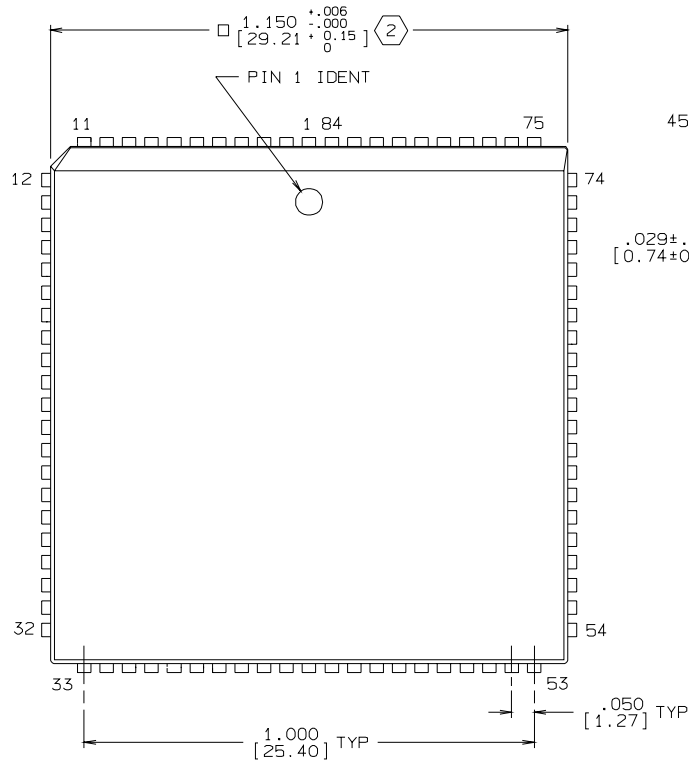


R E V I S I O N S				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE & REDRAW PER STD FORMAT	09326	09/24/92	TL/SL
F	ADD COPLANARITY & SEATING PLANE; CONVERT LIMIT DIM'S TO NOM±TOL.	10031	12/06/93	MS/



CONTROLLING DIMENSION: INCH

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH:  
200 MICROINCHES / 5.08 MICROMETERS MINIMUM SOLDER  
THICKNESS PER SIDE ON COPPER (Cu).

② DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25 mm  
PER SIDE.

3. REFERENCE JEDEC REGISTRATION MO-047, VARIATION AF,  
DATED 5/90.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION	
DRAWN T. LEQUANG	09/24/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090	
DFTG. CHK.		PLASTIC CHIP CARRIER, SQ, .050 LD PITCH, 84 LEAD	
ENGR. CHK.			
APPROVAL			
PROJECTION	SCALE	SIZE	DRAWING NUMBER
	N/A	C	MKT-V84A
	DO NOT SCALE DRAWING	SHEET	1 OF 1
		REV	F